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Reducing toxic effect of seed-soaked Cu fertilizer on germination of wheat

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ABSTRACT

A laboratory incubation experiment (20°C) was conducted to find if the detrimental effects of seed-soaked Cu on wheat seedlings can be minimized by reducing time duration of seed in contact with Cu EDTA fertilizer solution. The 24 treatments in a 6 x 4 factorial arrangement included 6 rates/amounts of Cu (0, 15, 30, 60, 120 and 240 g Cu 100 kg⁻¹ seed) and 4 seed-soaking time durations (0, 4, 8 and 16 h). The germination of wheat seed was 100% in the zero-Cu control treatments, irrespective of the duration of seed soaking time. However, seed germination decreased with increasing amount of fertilizer Cu in the seed-soaking solution, and the magnitude of reduction in seed germination due to Cu toxicity increased with increasing duration of seed-soaking time in the Cu fertilizer solution. For the seed-soaked treatments, the detrimental effect of Cu on germination was greatest with 16 h soaking, where only 13% - 18% of the seeds germinated with Cu applied at 15 to 30 g Cu 100 kg⁻¹ seed. For the 4 and 8 h seed soaking treatments, germination of wheat seed ranged from 73% to 83% with 15 g Cu 100 kg⁻¹ seed treatment and 42% to 62% with 30 g Cu 100 kg⁻¹ seed. The findings suggest that the detrimental effect of Cu on germination of wheat seed soaked in Cu EDTA solution can be decreased by reducing duration of soaking time from 16 h to 4 or 8 h, but this needs further investigation using soil under growth chamber and/or field conditions in order to make valid recommendations for use of this new technology on a commercial scale.

KEYWORDS

Amount/rate of Cu; Seed-Soaked Cu; Soaking Time/Duration, Solution Cu

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